Schottky Barrier Diode

NSR0170P2

Schottky barrier diodes are optimized for very low forward voltage drop and low leakage current and are used in a wide range of dc-dc converter, clamping and protection applications in portable devices. NSR0170P2 in a SOD-923 miniature package enables designers to meet the challenging task of achieving higher efficiency and meeting reduced space requirements.

Features

- Very Low Forward Voltage Drop 560 mV @ 10 mA
- Low Reverse Current 25 nA @ 50 V VR
- 70 mA of Continuous Forward Current
- Power Dissipation of 240 mW with Minimum Trace
- Very High Switching Speed
- Low Capacitance CT = 2 pF
- NSVR Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

Markets

- Mobile Handsets
- MP3 Players
- Digital Camera and Camcorders
- Notebook PCs & PDAs
- GPS

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	V _R	70	V
Forward Current (DC)	ΙF	70	mA
ESD Rating: Human Body Model Machine Model	ESD	Class 2 Class B	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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70 V SCHOTTKY BARRIER DIODE







MARKING

Q = Specific Device Code

M = Month Code

ORDERING INFORMATION

Device	Package	Shipping†
NSR0170P2T5G	SOD-923 (Pb-Free)	2 mm Pitch 8000/Tape & Reel
NSVR0170P2T5G	SOD-923 (Pb-Free)	2 mm Pitch 8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NSR0170P2

THERMAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ T _A = 25°C	R _{θJA} P _D			520 240	°C/W mW
Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ T _A = 25°C	R _{θJA} P _D			175 710	°C/W mW
Junction and Storage Temperature Range	T _J , T _{stg}			-55 to +150	°C

- Mounted onto a 4 in square FR-4 board 10 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
 Mounted onto a 4 in square FR-4 board 1 in sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Leakage (V _R = 50 V) (V _R = 70 V)	I _R		25 -	90 3.0	nΑ μΑ
Forward Voltage (I _F = 1.0 mA) (I _F = 10 mA) (I _F = 15 mA)	V _F		0.34 0.56 0.65	0.39 0.64 0.73	V
Total Capacitance (V _R = 0 V, f = 1 MHz)	СТ		2.0		pF

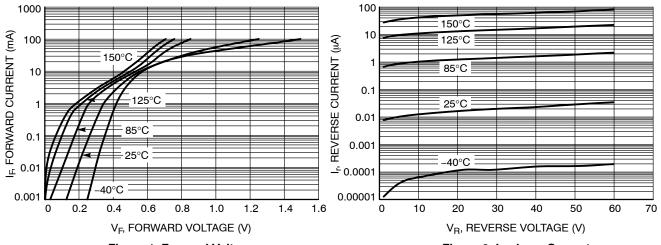


Figure 1. Forward Voltage

Figure 2. Leakage Current

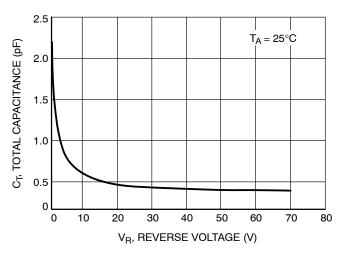


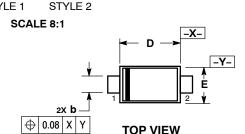
Figure 3. Total Capacitance

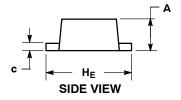


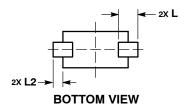


SOD-923 CASE 514AB ISSUE D

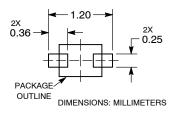
DATE 03 SEP 2020







SOLDERING FOOTPRINT*



See Application Note AND8455/D for more mounting details

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

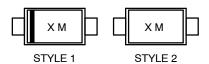
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD MAXIMUM LEAD I HICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

 DIMENSION L WILL NOT EXCEED 0.30mm.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	MOM	MAX
Α	0.34	0.37	0.40	0.013	0.015	0.016
b	0.15	0.20	0.25	0.006	800.0	0.010
С	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
Е	0.55	0.60	0.65	0.022	0.024	0.026
HE	0.95	1.00	1.05	0.037	0.039	0.041
L	0.19 REF		0	.007 RE	F	
L2	0.05	0.10	0.15	0.002	0.004	0.006

GENERIC MARKING DIAGRAM*



Χ = Specific Device Code

= Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

STYLE 2: NO POLARITY STYLE 1: PIN 1. CATHODE (POLARITY BAND) 2. ANODE

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DESCRIPTION:	SOD-923, 1.0X0.6X0.37, MA	X HEIGHT 0.40	PAGE 1 OF 1	

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